

Abstract

A bonding apparatus for bonding a plurality of dies to a target substrate includes: a substrate holder configured to hold the target substrate; and a head configured to bond the plurality of dies to the target substrate held by the substrate holder, wherein the head includes: a bond head configured to hold each of the plurality of dies and having electrical conductivity; an insulator configured to hold the bond head; and a ground connector configured to connect the bond head to a ground potential.

10 FIG. 10